

## **ABSTRACT**

### **WAFER DIVIDING METHOD AND WAFER DIVIDING APPARATUS**

Disclosed is a wafer dividing method including a mounting step of mounting a wafer accommodated in an annular frame through an adhesive tape on a dividing apparatus, an expanding step of expanding the adhesive tape by operating separating unit in a state in which no suction force of the wafer holding section is applied to the wafer mounted on the dividing apparatus to divide the wafer into individual chips and to form an interval between adjacent chips, a sucking and holding step of applying a suction force of the wafer holding section with the adhesive tape expanded to suck and hold the wafer through the adhesive tape, and a shrinking step of bringing the wafer holding section and the frame fixing section relatively closer to each other until the holding surface and the fixing surface are on the same level and heating a slaked portion of the adhesive tape between the wafer and the annular frame to shrink.

(Figure 2)